

Abstract of the Disclosure

Alternative designs, materials and manufacturing methods for medical devices. Some embodiments relate to a medical device including two or more components or structures that are connected through heat crimping. In some embodiments, the heat
5 crimping involves the use of a heat source to heat the material of one of the structures being connected to a point where it can flow or deform onto a surface of the other of the structures, and can thereafter be allowed to cool and form a mechanical bond between the two structures. In some embodiments, LASER energy is used as the heat source. Several alternative guidewire tip constructions and/or designs including methods and techniques
10 of construction are also disclosed.